

Welcome to **E-XFL.COM** 

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	CANbus, I <sup>2</sup> C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I <sup>2</sup> S, POR, PWM, WDT
Number of I/O	81
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 48x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx570f512lt-i-pf

TABLE 1-1: PINOUT I/O DESCRIPTIONS

	Pin N	umber			
Pin Name	64-pin QFN/ TQFP	100-pin TQFP	Pin Type	Buffer Type	Description
AN0	16	25	Ι	Analog	
AN1	15	24	I	Analog	
AN2	14	23	I	Analog	
AN3	13	22	I	Analog	
AN4	12	21	I	Analog	
AN5	11	20	I	Analog	
AN6	17	26	I	Analog	
AN7	18	27	I	Analog	
AN8	21	32	I	Analog	
AN9	22	33	I	Analog	
AN10	23	34	I	Analog	
AN11	24	35	I	Analog	
AN12	27	41	I	Analog	
AN13	28	42	I	Analog	
AN14	29	43	I	Analog	
AN15	30	44	I	Analog	
AN16	4	10	I	Analog	
AN17	5	11	I	Analog	A malan immut abannala
AN18	6	12	I	Analog	Analog input channels.
AN19	8	14	I	Analog	
AN20	62	98	I	Analog	
AN21	64	100	I	Analog	
AN22	1	3	I	Analog	
AN23	2	4	I	Analog	
AN24	49	76	I	Analog	
AN25	50	77	I	Analog	
AN26	51	78	I	Analog	
AN27	3	5	I	Analog	
AN28	_	1	I	Analog	
AN29	_	6	I	Analog	
AN30		7	I	Analog	
AN31	_	8	I	Analog	
AN32	_	18	I	Analog	
AN33	_	19	I	Analog	
AN34	_	39	I	Analog	
AN35	_	40	I	Analog	

Legend: CMOS = CMOS compatible input or output Analog = Analog input I = Input O = Output ST = Schmitt Trigger input with CMOS levels TTL = TTL input buffer P = Power

Note 1: This pin is only available on devices without a USB module.

- 2: This pin is only available on devices with a USB module.
- 3: This pin is not available on 64-pin devices with a USB module.
- **4:** This pin is only available on 100-pin devices without a USB module.

# 2.0 GUIDELINES FOR GETTING STARTED WITH 32-BIT MCUS

Note:

This data sheet summarizes the features of the PIC32MX1XX/2XX/5XX 64/100-pin family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the related section of the "PIC32 Family Reference Manual", which is available from the Microchip web site (www.microchip.com/PIC32).

#### 2.1 Basic Connection Requirements

Getting started with the PIC32MX1XX/2XX/5XX 64/ 100-pin family of 32-bit Microcontrollers (MCUs) requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names, which must always be connected:

- All VDD and Vss pins (see 2.2 "Decoupling Capacitors")
- All AVDD and AVSS pins, even if the ADC module is not used (see 2.2 "Decoupling Capacitors")
- VCAP pin (see 2.3 "Capacitor on Internal Voltage Regulator (VCAP)")
- MCLR pin (see 2.4 "Master Clear (MCLR) Pin")
- PGECx/PGEDx pins, used for In-Circuit Serial Programming (ICSP™) and debugging purposes (see 2.5 "ICSP Pins")
- OSC1 and OSC2 pins, when external oscillator source is used (see 2.7 "External Oscillator Pins")

The following pins may be required:

VREF+/VREF- pins, used when external voltage reference for the ADC module is implemented.

Note:

The AVDD and AVSS pins must be connected, regardless of ADC use and the ADC voltage reference source.

#### 2.2 Decoupling Capacitors

The use of decoupling capacitors on power supply pins, such as VDD, VSS, AVDD and AVSS is required. See Figure 2-1.

Consider the following criteria when using decoupling capacitors:

- Value and type of capacitor: A value of 0.1 µF (100 nF), 10-20V is recommended. The capacitor should be a low Equivalent Series Resistance (low-ESR) capacitor and have resonance frequency in the range of 20 MHz and higher. It is further recommended that ceramic capacitors be used
- Placement on the printed circuit board: The
  decoupling capacitors should be placed as close
  to the pins as possible. It is recommended that
  the capacitors be placed on the same side of the
  board as the device. If space is constricted, the
  capacitor can be placed on another layer on the
  PCB using a via; however, ensure that the trace
  length from the pin to the capacitor is within onequarter inch (6 mm) in length.
- Handling high frequency noise: If the board is experiencing high frequency noise, upward of tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 μF to 0.001 μF. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 μF in parallel with 0.001 μF.
- Maximizing performance: On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum thereby reducing PCB track inductance.

#### 2.5 ICSP Pins

The PGECx and PGEDx pins are used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (VIH) and input voltage low (VIL) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® ICD 3 or MPLAB REAL ICE $^{\text{TM}}$ .

For more information on MPLAB ICD 3 and MPLAB REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site

- "Using MPLAB® ICD 3" (poster) DS50001765
- "MPLAB® ICD 3 Design Advisory" DS50001764
- "MPLAB® REAL ICE™ In-Circuit Debugger User's Guide" DS50001616
- "Using MPLAB® REAL ICE™ Emulator" (poster) DS50001749

#### 2.6 JTAG

The TMS, TDO, TDI and TCK pins are used for testing and debugging according to the Joint Test Action Group (JTAG) standard. It is recommended to keep the trace length between the JTAG connector and the JTAG pins on the device as short as possible. If the JTAG connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms

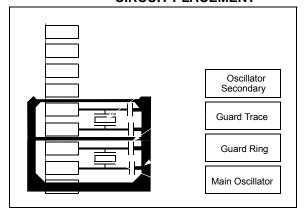
Pull-up resistors, series diodes and capacitors on the TMS, TDO, TDI and TCK pins are not recommended as they will interfere with the programmer or debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (VIH) and input voltage low (VIL) requirements

#### 2.7 External Oscillator Pins

Many MCUs have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator (refer to **Section 8.0 "Oscillator Configuration"** for details).

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is illustrated in Figure 2-3.

FIGURE 2-3: SUGGESTED OSCILLATOR CIRCUIT PLACEMENT



#### 4.0 MEMORY ORGANIZATION

Note:

This data sheet summarizes the features of the PIC32MX1XX/2XX/5XX 64/100-pin family of devices. It is not intended to be a comprehensive reference source. For detailed information, refer to **Section 3.** "**Memory Organization**" (DS60001115) in the "PIC32 Family Reference Manual", which is available from the Microchip web site (www.microchip.com/PIC32).

PIC32MX1XX/2XX/5XX 64/100-pin microcontrollers provide 4 GB of unified virtual memory address space. All memory regions, including program, data memory, SFRs and Configuration registers, reside in this address space at their respective unique addresses. The program and data memories can be optionally partitioned into user and kernel memories. In addition, the data memory can be made executable, allowing PIC32MX1XX/2XX/5XX 64/100-pin devices to execute from data memory.

The key features include:

- · 32-bit native data width
- Separate User (KUSEG) and Kernel (KSEG0/ KSEG1) mode address space
- · Flexible program Flash memory partitioning
- Flexible data RAM partitioning for data and program space
- · Separate boot Flash memory for protected code
- Robust bus exception handling to intercept runaway code
- Simple memory mapping with Fixed Mapping Translation (FMT) unit

#### 4.1 Memory Layout

PIC32MX1XX/2XX/5XX 64/100-pin microcontrollers implement two address schemes: virtual and physical. All hardware resources, such as program memory, data memory and peripherals, are located at their respective physical addresses. Virtual addresses are exclusively used by the CPU to fetch and execute instructions as well as access peripherals. Physical addresses are used by bus master peripherals, such as DMA and the Flash controller, that access memory independently of the CPU.

The memory maps for the PIC32MX1XX/2XX/5XX 64/ 100-pin devices are illustrated in Figure 4-1 through Figure 4-4.

TABLE 5-2: INTERRUPT REGISTER MAP (CONTINUED)

ess		•									Bits								
Virtual Address (BF88_#)	Register Name <sup>(3)</sup>	Bit Range	31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Resets
10E0	IPC5	31:16			-	Al	D1IP<2:0>		AD1IS	S<1:0>	1	_	_		OC5IP<2:0>	>	OC5IS	S<1:0>	0000
1000	IPC5	15:0	_	_	_	IC	C5IP<2:0>		IC5IS	<1:0>	_	_	_		T5IP<2:0>		T5IS	<1:0>	0000
10F0	IPC6	31:16	1	1	_	CM	1P1IP<2:0>		CMP1I	S<1:0>	_	_	_		FCEIP<2:0>	>	FCEIS	S<1:0>	0000
1010	IFC0	15:0	_	_	_	RT	CCIP<2:0>		RTCCI	S<1:0>	_	_	_		FSCMIP<2:0	>	FSCM	IS<1:0>	0000
1100	IPC7	31:16	_	_	_	U	11IP<2:0>		U1IS	<1:0>	_	_	_		SPI1IP<2:0	>	SPI1IS	S<1:0>	0000
1100	IFC1	15:0	-	-	_	US	BIP<2:0> <sup>(2)</sup>	)	USBIS	<1:0> <sup>(2)</sup>	_	_	_		CMP2IP<2:0	>	CMP2I	S<1:0>	0000
1110	IPC8	31:16	_	_	_	SF	PI2IP<2:0>		SPI2IS	S<1:0>	_	_	_		PMPIP<2:0	>	PMPI	S<1:0>	0000
1110	IFCo	15:0	_		_	C	NIP<2:0>		CNIS	<1:0>	_	_	_		I2C1IP<2:0	>	I2C1I	S<1:0>	0000
1120	IPC9	31:16		1		J	14IP<2:0>		U4IS	<1:0>	-	_	_		U3IP<2:0>		U3IS	<1:0>	0000
1120	11-09	15:0	_		_	120	C2IP<2:0>		12C2IS	S<1:0>	_	_	_		U2IP<2:0>		U2IS	<1:0>	0000
1130	IPC10	31:16	-	I	1	DM	1A1IP<2:0>		DMA1I	S<1:0>	I	_	-		DMA0IP<2:0	>	DMA0I	S<1:0>	0000
1130	IFCIO	15:0	-		_	CT	MUIP<2:0>		CTMUI	S<1:0>	-	_	_		U5IP<2:0>		U5IS	<1:0>	0000
1140	IPC11	31:16	_		_	CA	NIP<2:0> <sup>(5)</sup>	)	CANIS	<1:0> <sup>(5)</sup>	_	_	_		CMP3IP<2:0	>	CMP3I	S<1:0>	0000
1140	IFUII	15:0	_		_	DM	1A3IP<2:0>		DMA3I	S<1:0>	ı	_	_		DMA2IP<2:0	>	DMA2I	S<1:0>	0000
1150	IPC12	31:16		1		1	_	ı	_	-	-	_	_	_	_	_	_	_	0000
1130	IF U IZ	15:0	_		_	SP	14P<2:0> <sup>(1)</sup>		SPI4S<	<1:0> <sup>(1)</sup>	ı	_	_		SPI3P<2:0>	•	SPI39	S<1:0>	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This bit is only available on 100-pin devices.

- 2: This bit is only implemented on devices with a USB module.
- 3: With the exception of those noted, all registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4 0x8 and 0xC, respectively. See Section 11.2 "CLR, SET, and INV Registers" for more information.
- 4: This register does not have associated CLR, SET, and INV registers.
- 5: This bit is only implemented on devices with a CAN module.

#### 6.0 FLASH PROGRAM MEMORY

Note:

This data sheet summarizes the features of the PIC32MX1XX/2XX/5XX 64/100-pin family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 5.** "Flash **Program Memory**" (DS60001121) in the "PIC32 Family Reference Manual", which is available from the Microchip web site (www.microchip.com/PIC32).

PIC32MX1XX/2XX/5XX 64/100-pin devices contain an internal Flash program memory for executing user code. There are three methods by which the user can program this memory:

- Run-Time Self-Programming (RTSP)
- · EJTAG Programming
- In-Circuit Serial Programming™ (ICSP™)

RTSP is performed by software executing from either Flash or RAM memory. Information about RTSP techniques is available in **Section 5.** "Flash Program Memory" (DS60001121) in the "PIC32 Family Reference Manual".

EJTAG is performed using the EJTAG port of the device and an EJTAG capable programmer.

ICSP is performed using a serial data connection to the device and allows much faster programming times than RTSP.

The EJTAG and ICSP methods are described in the "PIC32 Flash Programming Specification" (DS60001145), which can be downloaded from the Microchip web site.

Note:

On PIC32MX1XX/2XX/5XX 64/100-pin devices, the Flash page size is 1 KB and the row size is 128 bytes (256 IW and 32 IW, respectively).

#### REGISTER 10-2: U10TGIE: USB OTG INTERRUPT ENABLE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
31.24	-	-	1	-	-	_	_	-
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
23.10	-		-	-	-	_	_	_
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
15.6	_	_	_	_	_	_	_	_
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0
7:0	IDIE	T1MSECIE	LSTATEIE	ACTVIE	SESVDIE	SESENDIE	_	VBUSVDIE

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'

-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 31-8 Unimplemented: Read as '0'

bit 7 IDIE: ID Interrupt Enable bit

1 = ID interrupt enabled0 = ID interrupt disabled

bit 6 T1MSECIE: 1 Millisecond Timer Interrupt Enable bit

1 = 1 millisecond timer interrupt enabled0 = 1 millisecond timer interrupt disabled

bit 5 LSTATEIE: Line State Interrupt Enable bit

1 = Line state interrupt enabled

0 = Line state interrupt disabled

bit 4 ACTVIE: Bus Activity Interrupt Enable bit

1 = ACTIVITY interrupt enabled

0 = ACTIVITY interrupt disabled

bit 3 SESVDIE: Session Valid Interrupt Enable bit

1 = Session valid interrupt enabled

0 = Session valid interrupt disabled

bit 2 SESENDIE: B-Session End Interrupt Enable bit

1 = B-session end interrupt enabled

0 = B-session end interrupt disabled

bit 1 Unimplemented: Read as '0'

bit 0 VBUSVDIE: A-VBUS Valid Interrupt Enable bit

1 = A-VBUS valid interrupt enabled

0 = A-VBUS valid interrupt disabled

#### 12.2 Control Registers

#### TABLE 12-1: TIMER1 REGISTER MAP

ess		0								Ві	its								s
Virtual Address (BF80_#)	Register Name <sup>(1)</sup>	Bit Range	31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Resets
0600	T1CON	31:16	_	_		_	_	_			_		_	_	_	_	_	_	0000
0600	TICON	15:0	ON	_	SIDL	TWDIS	TWIP	_	_	_	TGATE	_	TCKPS	S<1:0>	_	TSYNC	TCS	_	0000
0610	TMR1	31:16	1	_	_	_	_	_	_	_	_	_	_	_	_	_	_	_	0000
0010	TIVITY	15:0								TMR1	<15:0>								0000
0620	PR1	31:16	_	_	I	_	_	_		-	_	-	_	_	_	_	_	_	0000
0020	1 181	15:0								PR1<	15:0>								FFFF

**Legend:** x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See Section 11.2 "CLR, SET, and INV Registers" for more information.

#### REGISTER 17-3: SPIXSTAT: SPI STATUS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
24.24	U-0	U-0	U-0	R-0	R-0	R-0	R-0	R-0
31:24		_	-		R)	XBUFELM<4:0	)>	
22.46	U-0	U-0	U-0	R-0	R-0	R-0	R-0	R-0
23:16	_	_	_		T	(BUFELM<4:0	)>	
45.0	U-0	U-0	U-0	R/C-0, HS	R-0	U-0	U-0	R-0
15:8		_	ı	FRMERR	SPIBUSY	ı	1	SPITUR
7.0	R-0	R/W-0	R-0	U-0	R-1	U-0	R-0	R-0
7:0	SRMT	SPIROV	SPIRBE	_	SPITBE		SPITBF	SPIRBF

Legend:C = Clearable bitHS = Set in hardwareR = Readable bitW = Writable bitU = Unimplemented bit, read as '0'-n = Value at POR'1' = Bit is set'0' = Bit is clearedx = Bit is unknown

bit 31-29 Unimplemented: Read as '0'

bit 28-24 **RXBUFELM<4:0>:** Receive Buffer Element Count bits (valid only when ENHBUF = 1)

bit 23-21 Unimplemented: Read as '0'

bit 20-16 **TXBUFELM<4:0>:** Transmit Buffer Element Count bits (valid only when ENHBUF = 1)

bit 15-13 Unimplemented: Read as '0'

bit 12 FRMERR: SPI Frame Error status bit

1 = Frame error detected

0 = No Frame error detected

This bit is only valid when FRMEN = 1.

bit 11 SPIBUSY: SPI Activity Status bit

1 = SPI peripheral is currently busy with some transactions

0 = SPI peripheral is currently idle

bit 10-9 **Unimplemented:** Read as '0' bit 8 **SPITUR:** Transmit Under Run bit

1 = Transmit buffer has encountered an underrun condition

0 = Transmit buffer has no underrun condition

This bit is only valid in Framed Sync mode; the underrun condition must be cleared by disabling (ON bit = 0) and re-enabling (ON bit = 1) the module, or writing a '0' to SPITUR.

bit 7 **SRMT:** Shift Register Empty bit (valid only when ENHBUF = 1)

1 = When SPI module shift register is empty

0 = When SPI module shift register is not empty

bit 6 SPIROV: Receive Overflow Flag bit

1 = A new data is completely received and discarded. The user software has not read the previous data in the SPIxBUF register.

0 = No overflow has occurred

This bit is set in hardware; can bit only be cleared by disabling (ON bit = 0) and re-enabling (ON bit = 1) the module, or by writing a '0' to SPIROV.

bit 5 **SPIRBE:** RX FIFO Empty bit (valid only when ENHBUF = 1)

1 = RX FIFO is empty (CRPTR = SWPTR)

0 = RX FIFO is not empty (CRPTR ≠ SWPTR)

bit 4 Unimplemented: Read as '0'

#### REGISTER 20-7: PMSTAT: PARALLEL PORT STATUS REGISTER (SLAVE MODES ONLY)

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
24.24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
31:24	_	_	-	-	-		_	_
22.40	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
23:16	_	_	_	_	_	_	_	_
45.0	R-0	R/W-0, HSC	U-0	U-0	R-0	R-0	R-0	R-0
15:8	IBF	IBOV	-	-	IB3F	IB2F	IB1F	IB0F
7.0	R-1	R/W-0, HSC	U-0	U-0	R-1	R-1	R-1	R-1
7:0	OBE	OBUF			OB3E	OB2E	OB1E	OB0E

**Legend:** HSC = Set by Hardware; Cleared by Software

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'

-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 31-16 Unimplemented: Read as '0'

bit 15 IBF: Input Buffer Full Status bit

1 = All writable input buffer registers are full

0 = Some or all of the writable input buffer registers are empty

bit 14 IBOV: Input Buffer Overflow Status bit

1 = A write attempt to a full input byte buffer occurred (must be cleared in software)

0 = No overflow occurred

bit 13-12 Unimplemented: Read as '0'

bit 11-8 IBxF: Input Buffer 'x' Status Full bits

1 = Input Buffer contains data that has not been read (reading buffer will clear this bit)

0 = Input Buffer does not contain any unread data

bit 7 **OBE:** Output Buffer Empty Status bit

1 = All readable output buffer registers are empty

0 = Some or all of the readable output buffer registers are full

bit 6 **OBUF:** Output Buffer Underflow Status bit

1 = A read occurred from an empty output byte buffer (must be cleared in software)

0 = No underflow occurred

bit 5-4 Unimplemented: Read as '0'

bit 3-0 **OBxE:** Output Buffer 'x' Status Empty bits

1 = Output buffer is empty (writing data to the buffer will clear this bit)

0 = Output buffer contains data that has not been transmitted

#### REGISTER 21-6: ALRMDATE: ALARM DATE VALUE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
24.24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
31:24	_	_	_	_	_	_	_	_
22.46	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
23:16		MONT	H10<3:0>			MONTH	01<3:0>	
45.0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
15:8		DAY′	10<1:0>			DAY01	I<3:0>	
7.0	U-0	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x
7:0	_	_	_	_		WDAYO	1<3:0>	

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'

-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 31-24 Unimplemented: Read as '0'

bit 23-20 MONTH10<3:0>: Binary Coded Decimal value of months bits, 10s place digits; contains a value of 0 or 1

bit 19-16 MONTH01<3:0>: Binary Coded Decimal value of months bits, 1s place digit; contains a value from 0 to 9

bit 15-12 DAY10<3:0>: Binary Coded Decimal value of days bits, 10s place digits; contains a value from 0 to 3

bit 11-8 DAY01<3:0>: Binary Coded Decimal value of days bits, 1s place digit; contains a value from 0 to 9

bit 7-4 Unimplemented: Read as '0'

bit 3-0 WDAY01<3:0>: Binary Coded Decimal value of weekdays bits, 1s place digit; contains a value from 0 to 6

#### REGISTER 22-4: AD1CHS: ADC INPUT SELECT REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
24.04	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
31:24	CH0NB	_			CH0S	B<5:0>		
00.40	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
23:16	CH0NA	_			CH0S	A<5:0>		
45.0	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
15:8	_	_	_	_	_	_	_	_
7.0	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
7:0	_	_	_	_	_	_	_	_

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'

-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 31 CH0NB: Negative Input Select bit for Sample B

1 = Channel 0 negative input is AN1

0 = Channel 0 negative input is VREFL

bit 30 Unimplemented: Read as '0'

bit 29-24 CH0SB<5:0>: Positive Input Select bits for Sample B

For 64-pin devices:

011110 = Channel 0 positive input is Open(1)

011101 = Channel 0 positive input is CTMU temperature sensor (CTMUT)(2)

011100 = Channel 0 positive input is IVREF<sup>(3)</sup>

011011 = Channel 0 positive input is AN27

•

000001 = Channel 0 positive input is AN1

000000 = Channel 0 positive input is AN0

For 100-pin devices:

110010 = Channel 0 positive input is Open<sup>(1)</sup>

110001 = Channel 0 positive input is CTMU temperature sensor (CTMUT)(2)

110000 = Channel 0 positive input is IVREF<sup>(3)</sup>

101111 = Channel 0 positive input is AN47

•

0000001 = Channel 0 positive input is AN1

0000000 = Channel 0 positive input is AN0

bit 23 **CHONA:** Negative Input Select bit for Sample A Multiplexer Setting<sup>(3)</sup>

1 = Channel 0 negative input is AN1

0 = Channel 0 negative input is VREFL

bit 22 Unimplemented: Read as '0'

Note 1: This selection is only used with CTMU capacitive and time measurement.

2: See Section 26.0 "Charge Time Measurement Unit (CTMU)" for more information.

3: Internal precision 1.2V reference. See **Section 24.0 "Comparator"** for more information.

#### REGISTER 23-2: C1CFG: CAN BAUD RATE CONFIGURATION REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
31.24	_	_	_	_	-	_	_	_
23:16	U-0	R/W-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
23.10	_	WAKFIL	_	_	_	SEG	S2PH<2:0> <sup>(1</sup>	,4)
45.0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
15:8	SEG2PHTS <sup>(1)</sup>	SAM <sup>(2)</sup>	(	SEG1PH<2:0	>	Р	RSEG<2:0>	
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
7:0	SJW<1:	0>(3)			BRP<	5:0>		

Legend:HC = Hardware ClearS = Settable bitR = Readable bitW = Writable bitU = Unimplemented bit, read as '0'-n = Value at POR'1' = Bit is set'0' = Bit is clearedx = Bit is unknown

bit 31-23 Unimplemented: Read as '0'

bit 22 WAKFIL: CAN Bus Line Filter Enable bit

1 = Use CAN bus line filter for wake-up

0 = CAN bus line filter is not used for wake-up

bit 21-19 Unimplemented: Read as '0'

bit 18-16 **SEG2PH<2:0>:** Phase Buffer Segment 2 bits<sup>(1,4)</sup>

111 = Length is 8 x TQ

•

•

 $000 = \text{Length is } 1 \times \text{TQ}$ 

bit 15 **SEG2PHTS:** Phase Segment 2 Time Select bit<sup>(1)</sup>

1 = Freely programmable

0 = Maximum of SEG1PH or Information Processing Time, whichever is greater

bit 14 SAM: Sample of the CAN Bus Line bit (2)

1 = Bus line is sampled three times at the sample point

0 = Bus line is sampled once at the sample point

bit 13-11 SEG1PH<2:0>: Phase Buffer Segment 1 bits(4)

111 = Length is 8 x TQ

•

•

000 = Length is 1 x TQ

**Note 1:** SEG2PH ≤ SEG1PH. If SEG2PHTS is clear, SEG2PH will be set automatically.

2: 3 Time bit sampling is not allowed for BRP < 2.

3:  $SJW \leq SEG2PH$ .

4: The Time Quanta per bit must be greater than 7 (that is, TQBIT > 7).

**Note:** This register can only be modified when the CAN module is in Configuration mode (OPMOD<2:0> (C1CON<23:21>) = 100).

#### 24.1 Control Registers

#### TABLE 24-1: COMPARATOR REGISTER MAP

ess		•								Ві	ts								<b>"</b>
Virtual Address (BF80_#)	Register Name <sup>(1)</sup>	Bit Range	31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Resets
۸,000	CM1CON	31:16		_		_	_	_	_	_		_	_	_	_	_	_	_	0000
A000	CIVITCON	15:0	ON	COE	CPOL	_	_	_	_	COUT	EVPO	L<1:0>	_	CREF	_	_	CCH	<1:0>	E1C3
۸010	CM2CON	31:16	1	_	_	_	_	_	_	_	_	_	_	_	_	_	_	_	0000
AUTU	CIVIZCON	15:0	ON	COE	CPOL	_	_	_	_	COUT	EVPO	L<1:0>	_	CREF	_	_	CCH	<1:0>	E1C3
۸020	CM3CON	31:16	1	_	_	_	_	_	_	_	_	_	_	_	_	_	_	_	0000
A020	CIVISCOIN	15:0	ON	COE	CPOL	_	_	_	_	COUT	EVPO	L<1:0>	_	CREF	_	_	CCH-	<1:0>	E1C3
۸060	CMSTAT	31:16	_	_	_	_	_	_	_	_	_	_	_	_	_	_	_	_	0000
A000	CIVISTAT	15:0	_	_	SIDL	_	_	_	_	_	_	_	_	_	_	C3OUT	C2OUT	C1OUT	0000

**Legend:** x = unknown value on Reset; - = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See Section 11.2 "CLR, SET, and INV Registers" for more information.

PIC32MX1XX/2XX/5XX 64/100-PIN FAMILY

NOTES:

# 31.2 AC Characteristics and Timing Parameters

The information contained in this section defines PIC32MX1XX/2XX/5XX 64/100-pin AC characteristics and timing parameters.

FIGURE 31-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

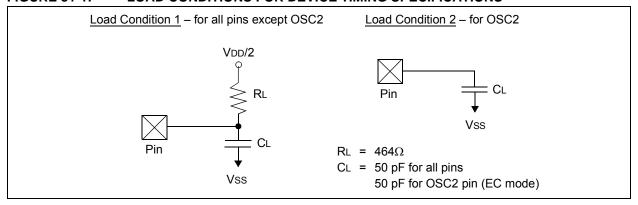
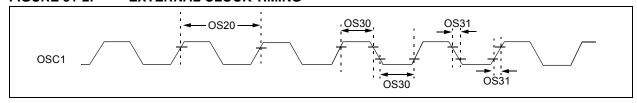


TABLE 31-16: CAPACITIVE LOADING REQUIREMENTS ON OUTPUT PINS

AC CHA	RACTERI	STICS	(unles	s otherwise	e stated ature -	<b>i)</b> -40°C ≤	: <b>2.3V to 3.6V</b> TA ≤ +85°C for Industrial TA ≤ +105°C for V-temp
Param. No.	Symbol	Characteristics	Min.	Typical <sup>(1)</sup>	Max.	Units	Conditions
DO50	Cosco	OSC2 pin	_	_	15		In XT and HS modes when an external crystal is used to drive OSC1
DO50a	Csosc	SOSCI/SOSCO pins	_	33	_	pF	Epson P/N: MC-306 32.7680K- A0:ROHS
DO56	Сю	All I/O pins and OSC2	_	_	50	pF	EC mode
DO58	Св	SCLx, SDAx	_	_	400	pF	In I <sup>2</sup> C mode

**Note 1:** Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

#### FIGURE 31-2: EXTERNAL CLOCK TIMING



SP60 SSx **SCKx** (CKP = 0)sė†z SP73 SCKx (CKP = 1)MSb Bit 14 -LSb SDOx SP30,SP31 SP51 SDIx MSb In Bit 14 LSb In SP40

FIGURE 31-13: SPIX MODULE SLAVE MODE (CKE = 1) TIMING CHARACTERISTICS

TABLE 31-31: SPIx MODULE SLAVE MODE (CKE = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}C \le TA \le +85^{\circ}C$ for Industrial $-40^{\circ}C \le TA \le +105^{\circ}C$ for V-temp				
Param. No.	Symbol	Characteristics <sup>(1)</sup>	Min.	Typical <sup>(2)</sup>	Max.	Units	Conditions
SP70	TscL	SCKx Input Low Time (Note 3)	Tsck/2	_	_	ns	_
SP71	TscH	SCKx Input High Time (Note 3)	Tsck/2	_	_	ns	_
SP72	TscF	SCKx Input Fall Time		5	10	ns	_
SP73	TscR	SCKx Input Rise Time		5	10	ns	_
SP30	TDOF	SDOx Data Output Fall Time (Note 4)				ns	See parameter DO32
SP31	TDOR	SDOx Data Output Rise Time (Note 4)	_	_	_	ns	See parameter DO31
SP35	TscH2DoV, TscL2DoV	SDOx Data Output Valid after SCKx Edge	_	_	20	ns	VDD > 2.7V
			_	_	30	ns	VDD < 2.7V
SP40	TDIV2scH, TDIV2scL	Setup Time of SDIx Data Input to SCKx Edge	10	_	_	ns	_
SP41	TscH2DIL, TscL2DIL	Hold Time of SDIx Data Input to SCKx Edge	10	_	_	ns	_
SP50	TssL2scH, TssL2scL	SSx ↓ to SCKx ↓ or SCKx ↑ Input	175	_		ns	_

Note 1: These parameters are characterized, but not tested in manufacturing.

- Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.
- 3: The minimum clock period for SCKx is 50 ns.
- Assumes 50 pF load on all SPIx pins.

TABLE 31-32: I2Cx BUS DATA TIMING REQUIREMENTS (MASTER MODE) (CONTINUED)

AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \le \text{TA} \le +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \le \text{TA} \le +105^{\circ}\text{C}$ for V-temp			
Param. No.	Symbol	Charac	teristics	Min. <sup>(1)</sup>	Max.	Units	Conditions
IM40	TAA:SCL	Output Valid from Clock	100 kHz mode	_	3500	ns	_
			400 kHz mode	_	1000	ns	_
			1 MHz mode (Note 2)	_	350	ns	_
IM45	TBF:SDA	4	100 kHz mode	4.7		μS	The amount of time the bus must be free before a new transmission can start
			400 kHz mode	1.3	_	μS	
			1 MHz mode (Note 2)	0.5	_	μS	
IM50	Св	Bus Capacitive Loading		_	400	pF	_
IM51	TPGD	Pulse Gobbler Delay		52	312	ns	See Note 3

**Note 1:** BRG is the value of the I<sup>2</sup>C Baud Rate Generator.

<sup>2:</sup> Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

**<sup>3:</sup>** The typical value for this parameter is 104 ns.

#### **INDEX**

A		CTMU	
AC Characteristics	321. 356	Registers	
10-Bit Conversion Rate Parameters	*	Customer Change Notification Service	
ADC Specifications		Customer Notification Service	377
Analog-to-Digital Conversion Requirements		Customer Support	377
EJTAG Timing Requirements		D	
Internal FRC Accuracy		_	
Internal RC Accuracy		DC and AC Characteristics	
OTG Electrical Specifications		Graphs and Tables	
Parallel Master Port Read Requirements		DC Characteristics	
Parallel Master Port Write		I/O Pin Input Specifications	
Parallel Master Port Write Requirements		I/O Pin Output Specifications	
Parallel Slave Port Requirements		Idle Current (IDLE)	313
•		Power-Down Current (IPD)	314
PLL Clock Timing		Program Memory	318
Analog-to-Digital Converter (ADC)	231	Temperature and Voltage Specifications	311
В		DC Characteristics (50 MHz)	354
Plack Diagrams		Idle Current (IIDLE)	355
Block Diagrams	024	Power-Down Current (IPD)	
ADC Module		Development Support	
Comparator I/O Operating Modes		Direct Memory Access (DMA) Controller	
Comparator Voltage Reference			
Connections for On-Chip Voltage Regulator		E	
CPU	35	Electrical Characteristics	309
CTMU Configurations		50 MHz	
Time Measurement		Errata	
DMA		External Clock	•
Input Capture		Timer1 Timing Requirements	327
Inter-Integrated Circuit (I <sup>2</sup> C)		Timer2, 3, 4, 5 Timing Requirements	
Interrupt Controller		Timing Requirements	
JTAG Programming, Debugging and Trace P		External Clock (50 MHz)	022
Output Compare Module	177	Timing Requirements	356
PIC32 CAN Module	243	Tilling Requirements	000
PMP Pinout and Connections to External Dev	rices 207	F	
Reset System	69	Flash Program Memory	63
RTCC	221	RTSP Operation	
SPI Module	181	Teror operation	00
Timer1	159	Н	
Timer2/3/4/5 (16-Bit)	163	High Voltage Detect (HVD)	71 302
Typical Multiplexed Port Structure	129	riigir voitage zotoot (rivz)	, , , , ,
UART	199	I	
WDT and Power-up Timer	169	I/O Ports	129
Brown-out Reset (BOR)		Parallel I/O (PIO)	
and On-Chip Voltage Regulator	302	Write/Read Timing	
		Input Change Notification	
C		Instruction Set	
C Compilers		Inter-Integrated Circuit (I <sup>2</sup> C)	
MPLAB C18	306	Internal Voltage Reference Specifications	
Charge Time Measurement Unit. See CTMU.		Internal Voltage Reference Specifications	
Clock Diagram	74		
Comparator		Interrupt Controller	
Specifications	319 320	IRG, Vector and Bit Location	54
Comparator Module		M	
Comparator Voltage Reference (CVref			
		Memory Maps	4.4
Configuration Bit  Configuring Analog Port Pins		Devices with 128 KB of Program Memory	
		Devices with 256 KB of Program Memory	
Controller Area Network (CAN)	243	Devices with 512 KB of Program Memory	
Arabitactura Ovaniaw	26	Devices with 64 KB of Program Memory	
Architecture Overview		Memory Organization	
Coprocessor 0 Registers		Layout	
Core Exception Types		Microchip Internet Web Site	
EJTAG Debug Support		MPASM Assembler	
Power Management		MPLAB ASM30 Assembler, Linker, Librarian	
CPU Module	25, 35	MPLAB Integrated Development Environment Softw	vare 305

MPLAB PM3 Device Programmer	307	AD1CHS (ADC Input Select)
MPLAB REAL ICE In-Circuit Emulator System		AD1CON1 (A/D Control 1)230
MPLINK Object Linker/MPLIB Object Librarian		AD1CON1 (ADC Control 1) 230, 235
		AD1CON2 (ADC Control 2)
0		AD1CON3 (ADC Control 3)
Oscillator Configuration	73	AD1CSSL (ADC Input Scan Select)
Output Compare	177	AD1CSSL2 (ADC Input Scan Select 2)
В		ALRMDATE (Alarm Date Value)230
P		ALRMDATECLR (ALRMDATE Clear) 230
Packaging		ALRMTIME (Alarm Time Value)
Details		ALRMTIMECLR (ALRMTIME Clear) 230
Marking		ALRMTIMEINV (ALRMTIME Invert)
Parallel Master Port (PMP)		ALRMTIMESET (ALRMTIME Set)230
PIC32 Family USB Interface Diagram		BMXBOOTSZ (Boot Flash (IFM) Size 51
Pinout I/O Descriptions (table)	14	BMXCON (Bus Matrix Configuration) 46
Power-on Reset (POR)		BMXDKPBA (Data RAM Kernel Program
and On-Chip Voltage Regulator		Base Address) 47
Power-Saving Features		BMXDRMSZ (Data RAM Size Register) 50
CPU Halted Methods		BMXDUDBA (Data RAM User Data Base Address) 48
Operation		BMXDUPBA (Data RAM User Program
with CPU Running	285	Base Address)
R		BMXPFMSZ (Program Flash (PFM) Size)51
Real-Time Clock and Calendar (RTCC)	221	BMXPUPBA (Program Flash (PFM) User Program
Register Map	22 1	Base Address)
ADC	233	CiCFG (CAN Baud Rate Configuration)
Bus Matrix		CiCON (CAN Module Control)
Comparator		CiFIFOBA (CAN Message Buffer Base Address) 265
Comparator Voltage Reference		CiFIFOCINn (CAN Module Message Index Register 'n')
CTMU		270
Device and Revision ID Summary		CIFIFOCONn (CAN FIFO Control Register 'n') 266
Device Configuration Word Summary		CiFIFOINTn (CAN FIFO Interrupt Register 'n') 268 CiFIFOUAn (CAN FIFO User Address Register 'n'). 270
DMA Channel 0-3		,
DMA CRC		CiFLTCON0 (CAN Filter Control 0)
DMA Global	86	CiFLTCON1 (CAN Filter Control 2)
Flash Controller	64	CiFLTCON3 (CAN Filter Control 3)
I2C1 and I2C2	193	CIFSTAT (CAN FIFO Status)253
Input Capture 1-5	174	CilNT (CAN Interrupt)
Interrupt	56	CiRXFn (CAN Acceptance Filter 'n')
Oscillator Configuration7	6, 170	CiRXMn (CAN Acceptance Filter Mask 'n')
Output Compare1-5	178	CiRXOVF (CAN Receive FIFO Overflow Status) 254
Parallel Master Port		CiTMR (CAN Timer)
Peripheral Pin Select Input		CiTREC (CAN Transmit/Receive Error Count) 253
Peripheral Pin Select Output		CiVEC (CAN Interrupt Code)252
PORTA (100-pin Devices Only)		CM1CON (Comparator 1 Control)
PORTB		CMSTAT (Comparator Control Register)274
PORTB (100-pin Devices Only)		CNCONx (Change Notice Control for PORTx) 158
PORTC (64-pin Devices Only)		CTMUCON (CTMU Control)281
PORTD (100-pin Devices Only)		CVRCON (Comparator Voltage Reference Control) 277
PORTD (64-pin Devices Only)		DCHxCON (DMA Channel x Control)95
PORTE (100-pin Devices Only)		DCHxCPTR (DMA Channel x Cell Pointer) 102
PORTE (400 pin Conord Burnage Povinge Only)		DCHxCSIZ (DMA Channel x Cell-Size)102
PORTF (100-pin General Purpose Devices Only)		DCHxDAT (DMA Channel x Pattern Data) 103
PORTF (100-pin USB Devices Only) PORTF (64-pin General Purpose Devices Only)		DCHxDPTR (Channel x Destination Pointer) 101
PORTF (64-pin USB Devices Only)		DCHxDSA (DMA Channel x Destination
PORTF (04-pin OSB Devices Only)		Start Address)
PORTG (64-pin Devices Only)		DCHxDSIZ (DMA Channel x Destination Size) 100
RTCC		DCHxECON (DMA Channel x Event Control)
SPI1 through SPI4		DCHxINT (DMA Channel x Interrupt Control)97
Timer1		DCHxSPTR (DMA Channel x Source Pointer) 101
Timer2-5		DCHxSSA (DMA Channel x Source Start Address) 99
UART1-5		DCHxSSIZ (DMA Channel x Source Size)
USB		DCRCCON (DMA CRC Control)
Registers		DCRCXOR (DMA CRCXOR Enable)
[pin name]R (Peripheral Pin Select Input)	157	BONONON (DIVIN ONONON ETIABLE)